



SF1125A

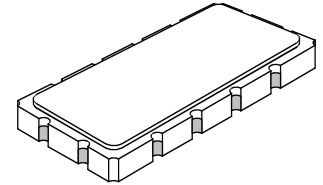
- **Designed for WCDMA 3G IF Applications**
- **Excellent Size-to-Performance Ratio**
- **Hermetic 13.3 x 6.5 mm Surface-mount Case**
- **Complies with Directive 2002/95/EC (RoHS)**



**380 MHz
SAW Filter**

Absolute Maximum Ratings

| Rating | Value | Units |
|---|----------------|-------|
| Maximum Incident Power in Passband | +10 | dBm |
| Max. DC voltage between any 2 terminals | 30 | VDC |
| Storage Temperature Range | -40 to +85 | °C |
| Suitable for lead-free soldering - Max. Soldering Profile | 260°C for 30 s | |



SMP-53

Electrical Characteristics

| Characteristic | Sym | Notes | Min | Typ | Max | Units | | | |
|--|--|-----------------|---------|------|------|--------|---|-----------------|------|
| Nominal Center Frequency | f_c | 1 | 380.000 | | | MHz | | | |
| Passband | Insertion Loss at f_c | IL | | 16.5 | 18 | dB | | | |
| | | | | | | | 1 db Passband | BW ₁ | 4.45 |
| | 3 db Passband | BW ₃ | 5.1 | 5.4 | | | | | |
| | Amplitude Ripple over $f_c \pm 2.25$ MHz | | 1, 2 | | 0.75 | 1.25 | dB _{p-p} | | |
| | Phase Linearity over $f_c \pm 2.25$ MHz | | | | 7.5 | TBD | ° _{p-p} | | |
| | Group Delay Variation over $f_c \pm 2.25$ MHz | GDV | | | 150 | 175 | ns _{p-p} | | |
| Rejection | $f_c - 3.95$ to $f_c - 3.33$ and $f_c + 3.3$ to $f_c + 3.95$ MHz | | 1, 2, 3 | 10 | | dB | | | |
| | | | | | | | $f_c - 4.125$ to $f_c - 3.95$ and $f_c + 3.95$ to $f_c + 4.125$ MHz | 30 | |
| | | | | | | | $f_c \pm 4.125$ to $f_c \pm 60$ MHz | 40 | |
| Part to Part Average Group Delay Variation | | 4 | | | ±5 | nsec | | | |
| Operating Temperature Range | T _A | 1 | -10 | +25 | +85 | °C | | | |
| Frequency Temperature Coefficient | FTC | | | -18 | | ppm/°C | | | |

| | |
|--|--|
| Matching to 50Ω Balanced or Single Ended Impedance | External L-C |
| Case Style | SMP-53 13.3 x 6.5 mm Nominal Footprint |
| Lid Symbolization (YY = year, WW = week) | RFM SF1125A YYWW |

Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. Part to part absolute delay measurement records the absolute delay mean across 1 dB passband.
5. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
6. The design, manufacturing process, and specifications of this filter are subject to change.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Electrostatic Sensitive Device. Observe precautions for handling.

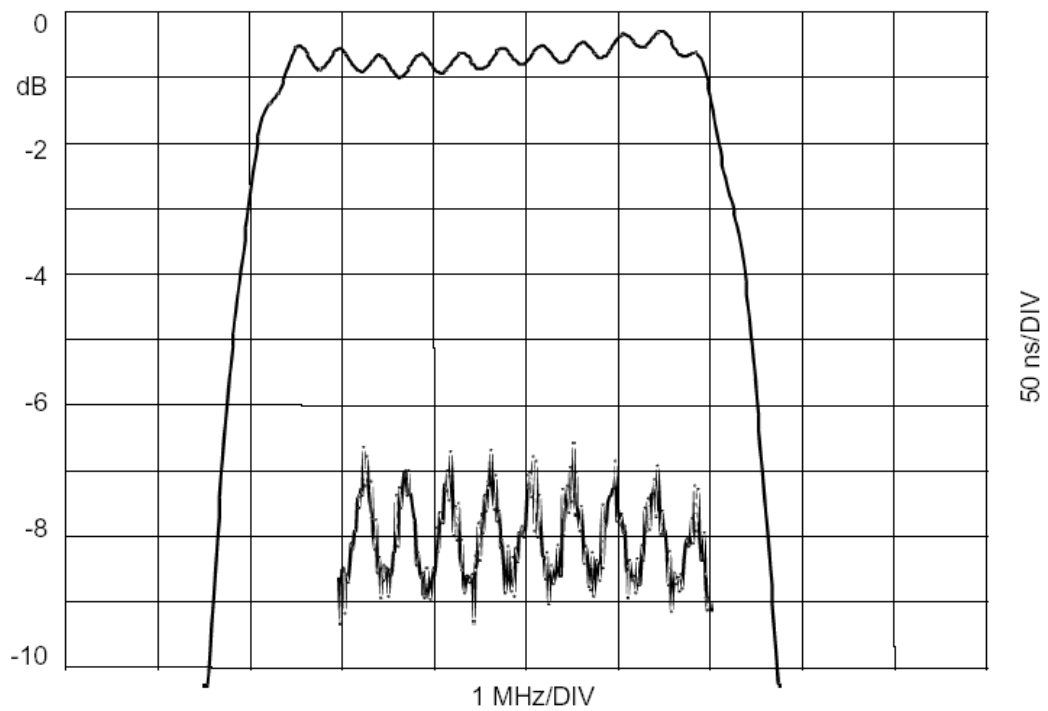
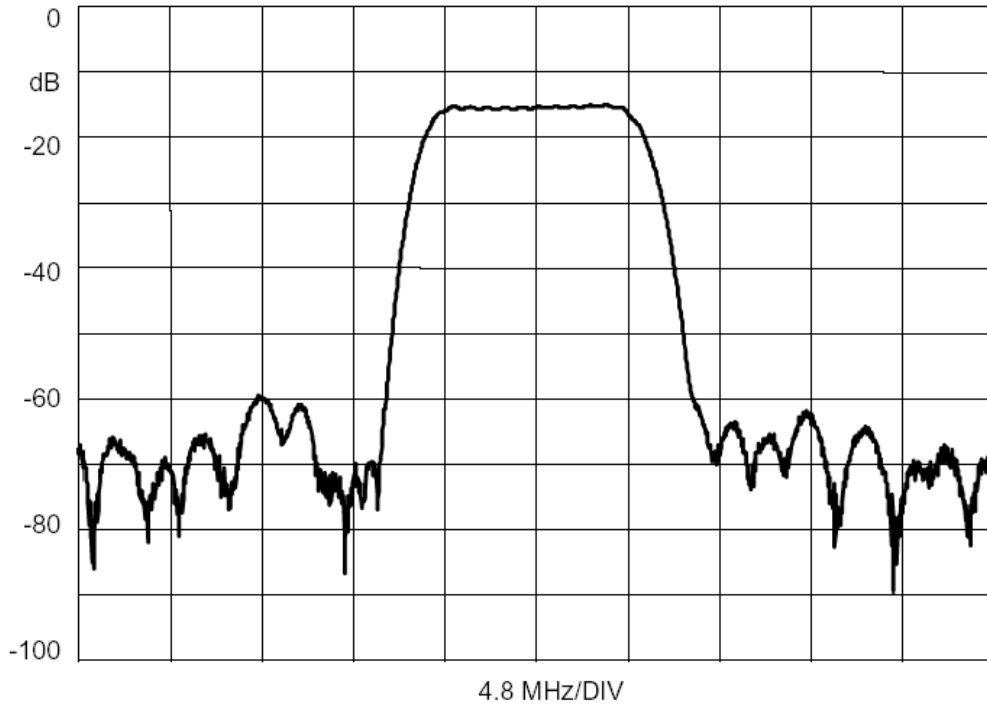


Electrical Connections

| Connection | Terminals |
|-------------------|------------|
| Port 1 Hot | 11 |
| Port 1 Gnd Return | 12 |
| Port 2 Hot | 5 |
| Port 2 Gnd Return | 6 |
| Case Ground | All others |

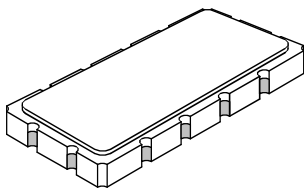
380.0 MHz

SAW Filter



SMP-53 Case

12-Terminal Ceramic Surface-Mount Case
13.3 x 6.5 mm Nominal Footprint



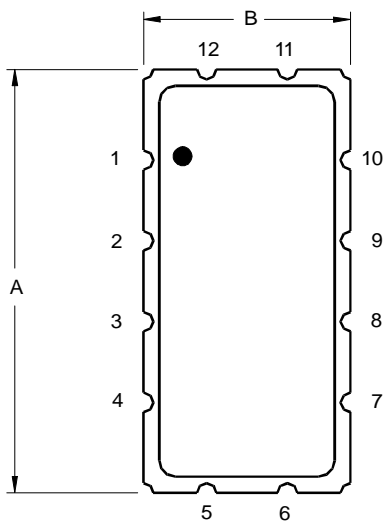
Case Dimensions

| Dimension | mm | | | Inches | | |
|-----------|-------|-------|-------|--------|-------|-------|
| | Min | Nom | Max | Min | Nom | Max |
| A | 13.08 | 13.31 | 13.60 | 0.515 | 0.524 | 0.535 |
| B | 6.27 | 6.50 | 6.80 | 0.247 | 0.256 | 0.268 |
| C | | 1.91 | 2.00 | | 0.075 | 0.079 |
| D | | 1.50 | | | 0.059 | |
| E | | 0.79 | | | 0.031 | |
| H | | 1.0 | | | 0.039 | |
| P | | 2.54 | | | 0.100 | |

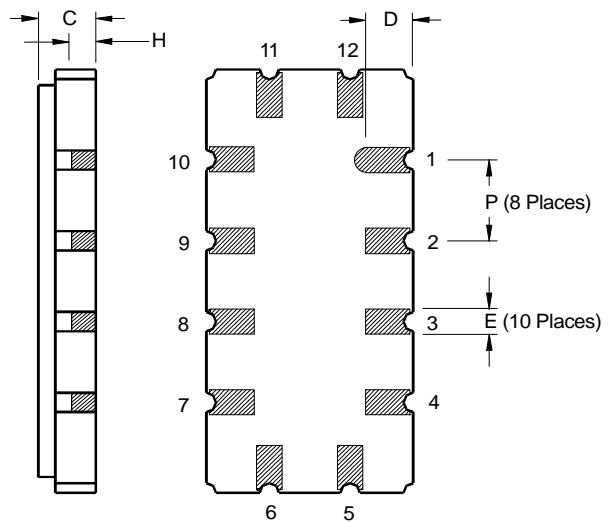
| Materials | |
|------------------------|--|
| Solder Pad Termination | Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni. |
| Lid | Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick |
| Body | Al ₂ O ₃ Ceramic |
| Pb Free | |

Electrical Connections

| Connection | | Terminals |
|------------------------|------------------|------------------|
| Port 1 | Input or Return | 11 |
| | Return or Input | 12 |
| Port 2 | Output or Return | 5 |
| | Return or Output | 6 |
| Ground | | All others |
| Single Ended Operation | | Return is ground |
| Differential Operation | | Return is hot |

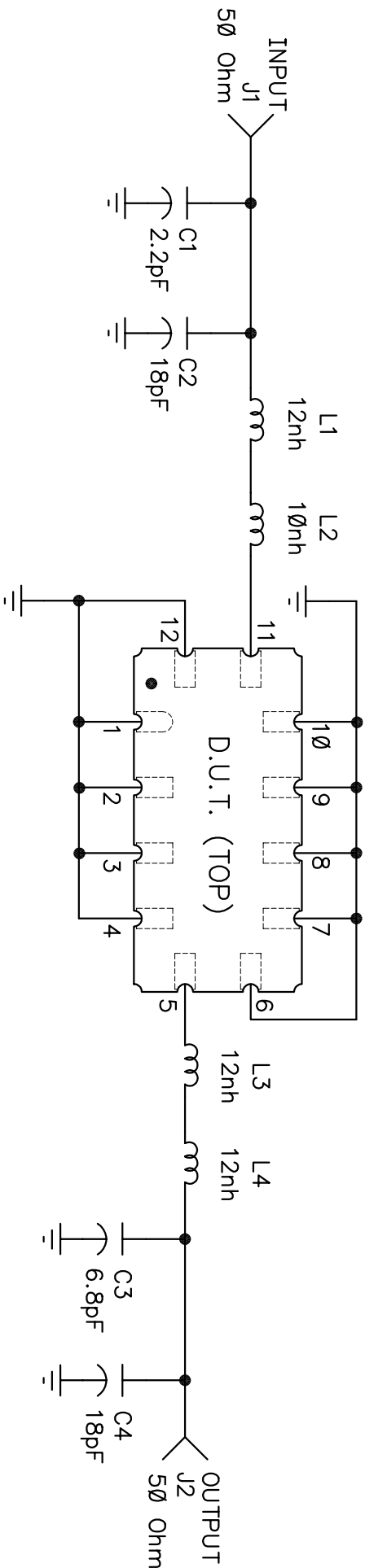


TOP VIEW



BOTTOM VIEW

| REV | ECN NO. | DESCRIPTION | APP/DATE |
|-----|---------|-----------------|----------|
| A | 9198 | INITIAL RELEASE | 27nov00 |



DRAWN BY/DATE: J.F.Christopherson 27nov00

TITLE:

SF1125A DEMO PCB

RF Monolithics, Inc.

CHECKED/APPROVED

SIZE

A

CODE IDENT

2U874

DWG. NO.

SF1125A-000

REV

A

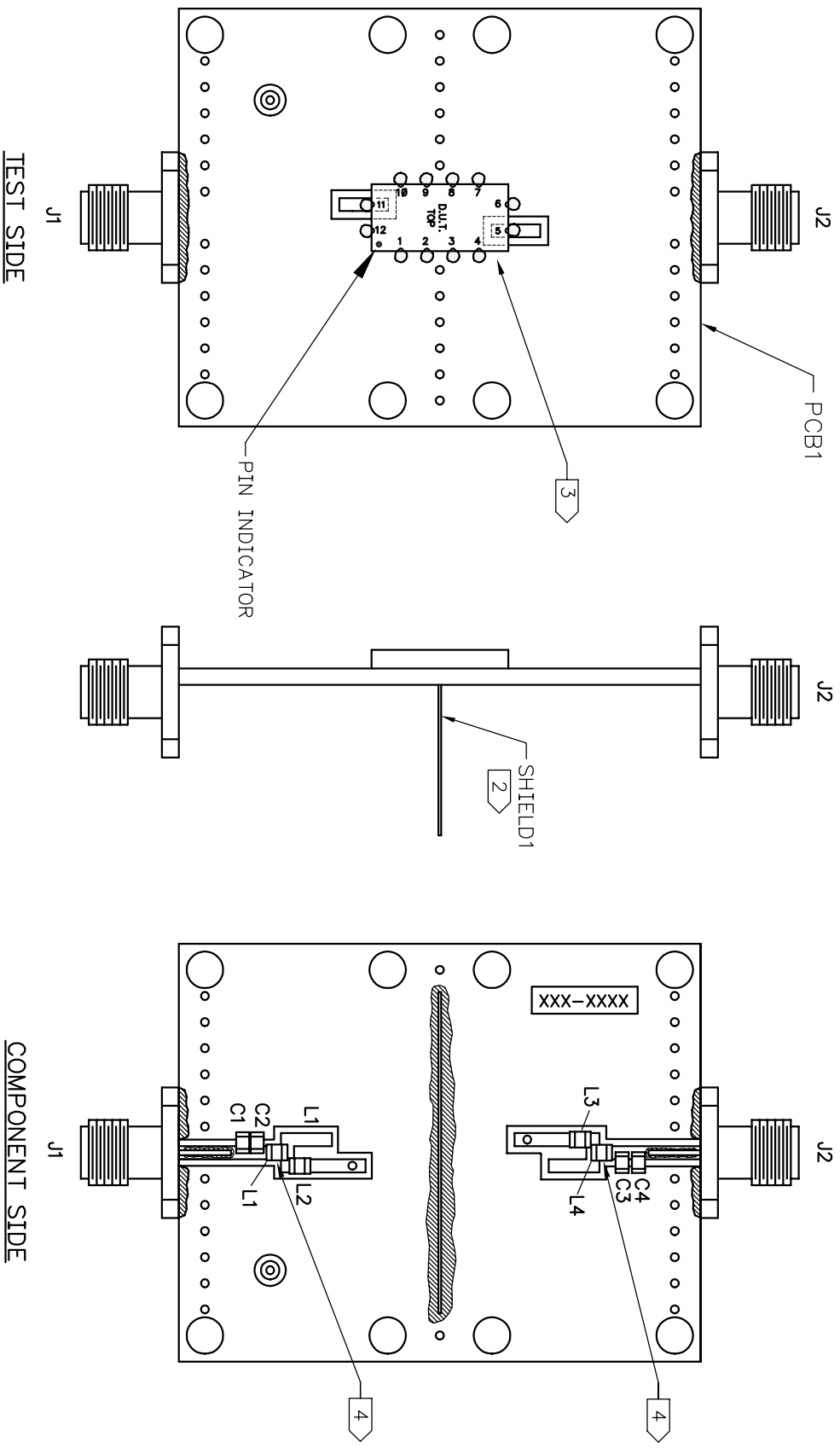
SHEET

1 / 3

DALLAS, TEXAS 75244

NOTES:

1. SOLDER MOUNT COMPONENTS & CONNECTORS TO PCB1.
2. SOLDER SHIELD1 AS SHOWN AND TRIM TAB FROM SHIELD SO THAT IT IS FLUSH WITH PCB.
3. ORIENT THE FLTR1 AND SOLDER IT DOWN TO THE BOARD AS SHOWN.
4. CUT TRACE TO ACCOMMODATE INDUCTOR.



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DALLAS, TEXAS 75244

SIZE
A

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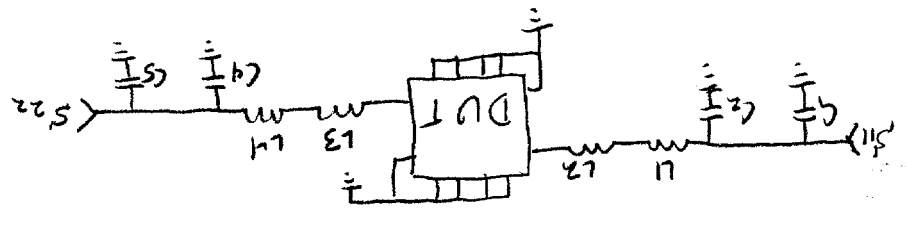
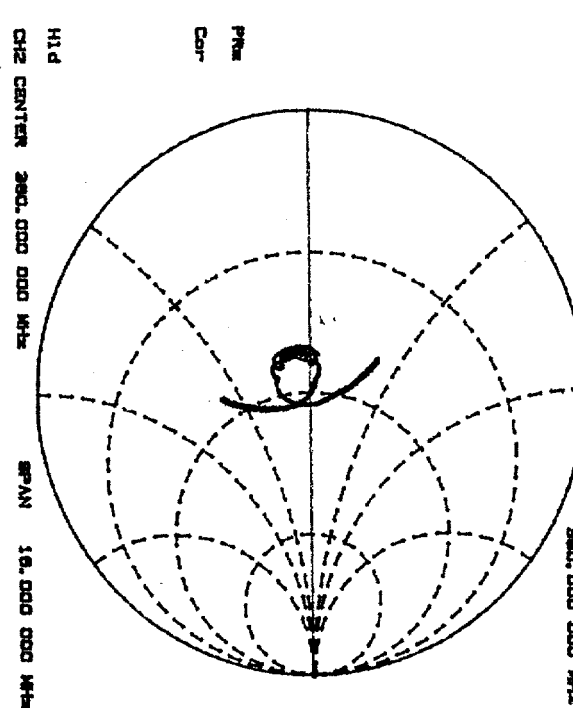
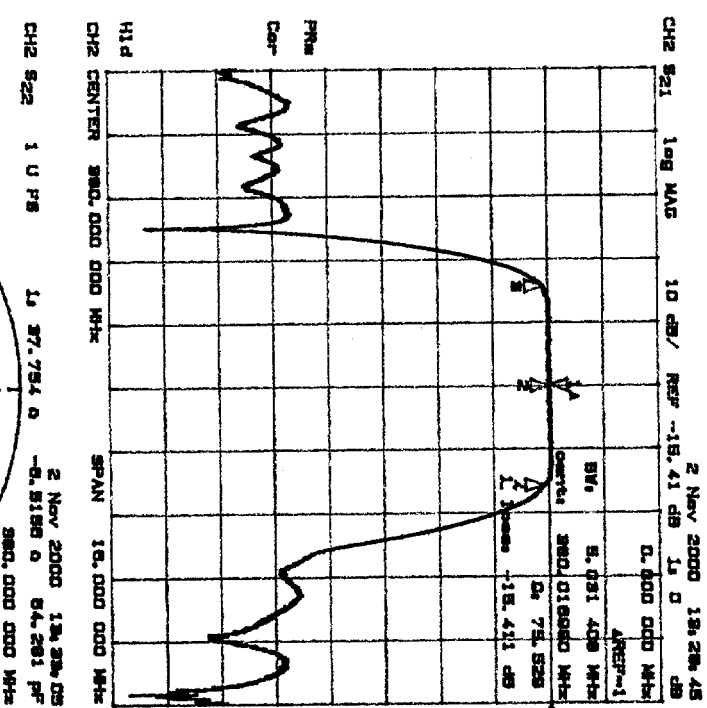
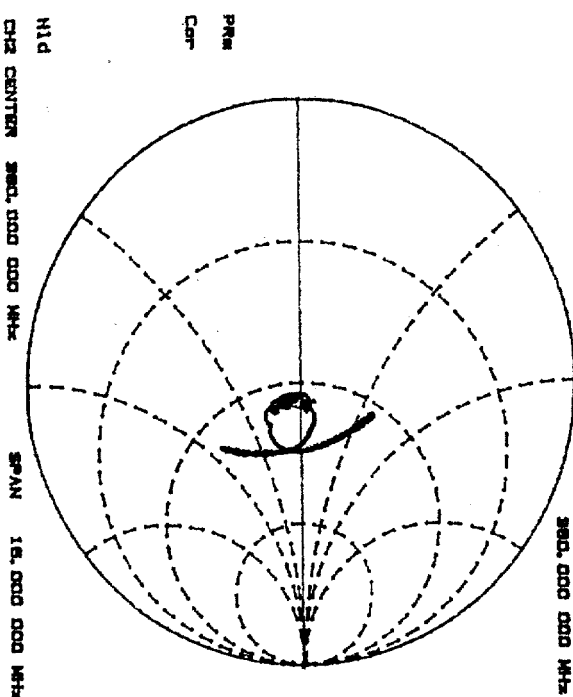
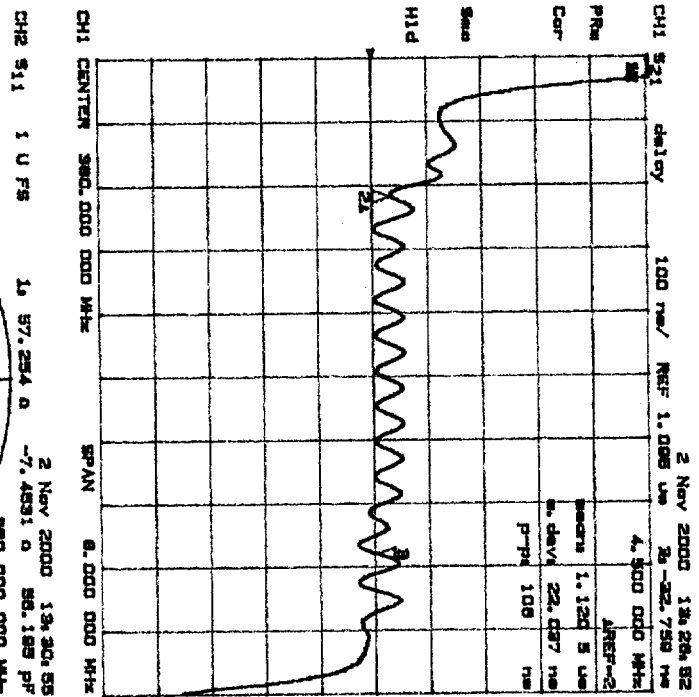
SF1125A-000

REV
A

SHEET
2

SF1125A
 DEMO 2

11-2-00
 RT



C1=2.2nF
 C2=C4=18pF
 C3=6.8pF
 L1,L3,L4=12nH
 L2=10nH